

General Description

FSMOS[®] MOSFET is based on Oriental Semiconductor's unique device design to achieve low $R_{DS(ON)}$, low gate charge, fast switching and excellent avalanche characteristics. The high V_{th} series is specially designed to use in motor control systems with driving voltage of more than 10V.

Features

- Low $R_{DS(ON)}$ & FOM
- Extremely low switching loss
- Excellent reliability and uniformity
- Fast switching and soft recovery



Applications

- PD charger
- Motor driver
- Switching voltage regulator
- DC-DC convertor
- Switching mode power supply

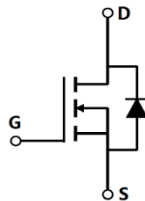
Key Performance Parameters

Parameter	Value	Unit
V_{DS}	100	V
I_D , pulse	1440	A
$R_{DS(ON)}$, max @ $V_{GS}=10V$	2	m Ω
Q_g	151.5	nC

Marking Information

Product Name	Package	Marking
SFS10R02K7NF	TO263-6L	SFS10R02K7N

Package & Pin information



Absolute Maximum Ratings at $T_j=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	100	V
Gate-source voltage	V_{GS}	± 20	V
Continuous drain current ¹⁾ , $T_C=25^\circ\text{C}$	I_D	360	A
Pulsed drain current ²⁾ , $T_C=25^\circ\text{C}$	$I_{D, pulse}$	1440	A
Continuous diode forward current ¹⁾ , $T_C=25^\circ\text{C}$	I_S	360	A
Diode pulsed current ²⁾ , $T_C=25^\circ\text{C}$	$I_{S, pulse}$	1440	A
Power dissipation ³⁾ , $T_C=25^\circ\text{C}$	P_D	600	W
Single pulsed avalanche energy ⁵⁾	E_{AS}	540	mJ
Operation and storage temperature	T_{stg}, T_j	-55 to 175	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal resistance, junction-case	$R_{\theta JC}$	0.25	$^\circ\text{C/W}$
Thermal resistance, junction-ambient ⁴⁾	$R_{\theta JA}$	62	$^\circ\text{C/W}$

Electrical Characteristics at $T_j=25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	BV_{DSS}	100			V	$V_{GS}=0\text{ V}, I_D=250\ \mu\text{A}$
Gate threshold voltage	$V_{GS(th)}$	2		4	V	$V_{DS}=V_{GS}, I_D=250\ \mu\text{A}$
Drain-source on-state resistance	$R_{DS(ON)}$		1.4	2	m Ω	$V_{GS}=10\text{ V}, I_D=50\text{ A}$
Gate-source leakage current	I_{GSS}			100	nA	$V_{GS}=20\text{ V}$
				-100		$V_{GS}=-20\text{ V}$
Drain-source leakage current	I_{DSS}			1	μA	$V_{DS}=100\text{ V}, V_{GS}=0\text{ V}$
Gate resistance	R_G		0.98		Ω	$f=1\text{ MHz}$, Open drain

Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C_{iss}		9950		pF	$V_{GS}=0\text{ V}$, $V_{DS}=25\text{ V}$, $f=100\text{ kHz}$
Output capacitance	C_{oss}		5510		pF	
Reverse transfer capacitance	C_{rss}		379		pF	
Turn-on delay time	$t_{d(on)}$		25		ns	$V_{GS}=10\text{ V}$, $V_{DS}=50\text{ V}$, $R_G=2\ \Omega$, $I_D=25\text{ A}$
Rise time	t_r		23		ns	
Turn-off delay time	$t_{d(off)}$		65		ns	
Fall time	t_f		30		ns	

Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q_g		151.5		nC	$V_{GS}=10\text{ V}$, $V_{DS}=50\text{ V}$, $I_D=25\text{ A}$
Gate-source charge	Q_{gs}		33.5		nC	
Gate-drain charge	Q_{gd}		33.7		nC	
Gate plateau voltage	$V_{plateau}$		3.7		V	

Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward voltage	V_{SD}			1.3	V	$I_S=30\text{ A}$, $V_{GS}=0\text{ V}$
Reverse recovery time	t_{rr}		112		ns	$V_R=50\text{ V}$, $I_S=25\text{ A}$, $di/dt=100\text{ A}/\mu\text{s}$
Reverse recovery charge	Q_{rr}		329		nC	
Peak reverse recovery current	I_{rrm}		4.8		A	

Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) P_d is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_a=25\text{ }^\circ\text{C}$.
- 5) $V_{DD}=50\text{ V}$, $V_{GS}=10\text{ V}$, $L=0.3\text{ mH}$, starting $T_j=25\text{ }^\circ\text{C}$.

Electrical Characteristics Diagrams

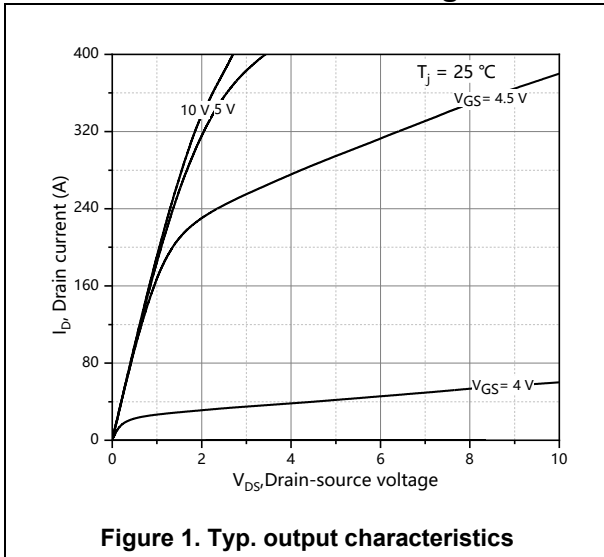


Figure 1. Typ. output characteristics

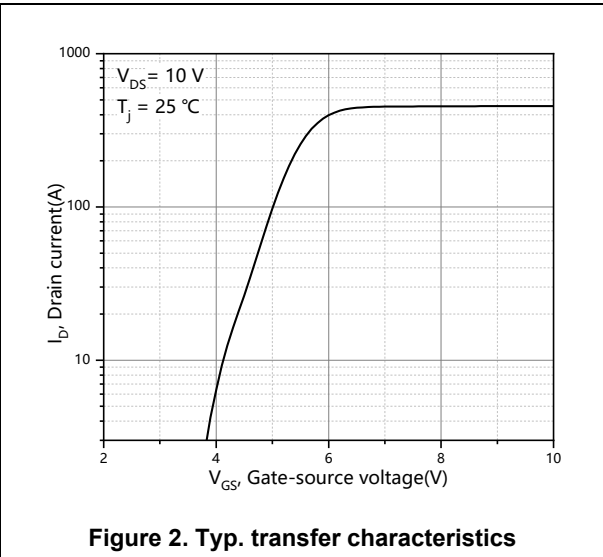


Figure 2. Typ. transfer characteristics

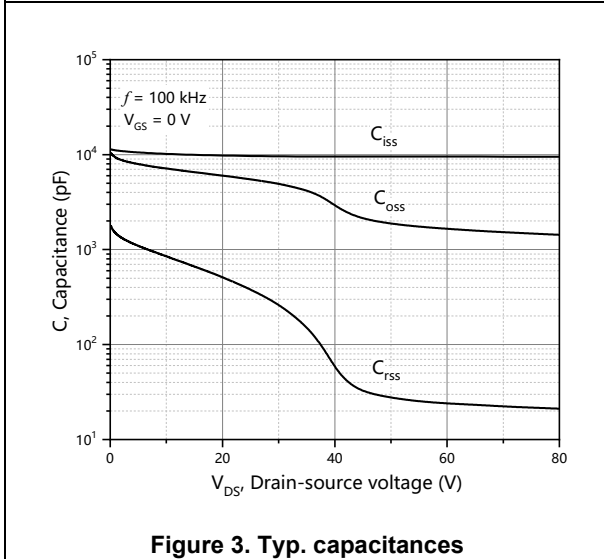


Figure 3. Typ. capacitances

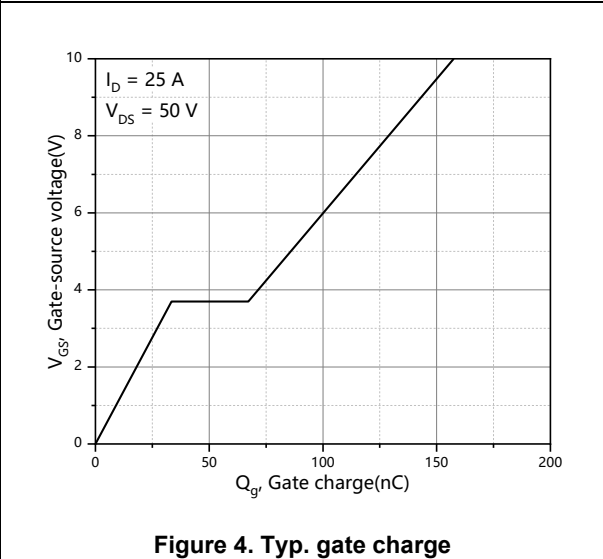


Figure 4. Typ. gate charge

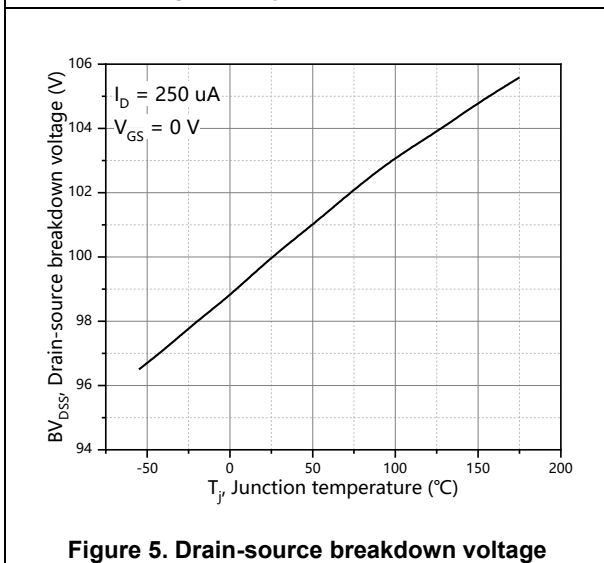


Figure 5. Drain-source breakdown voltage

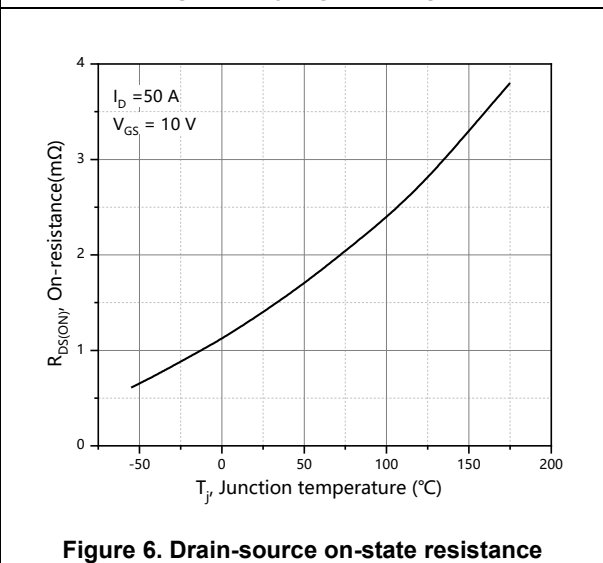
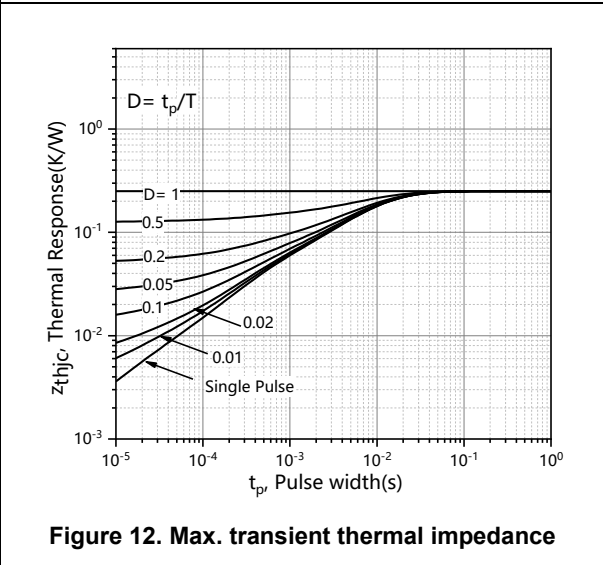
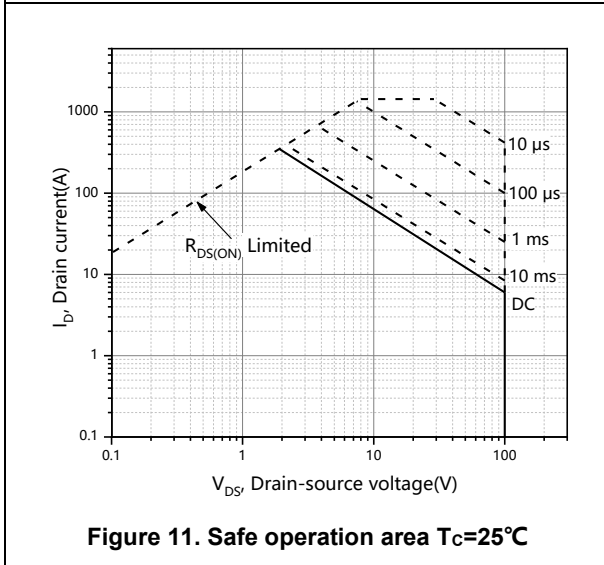
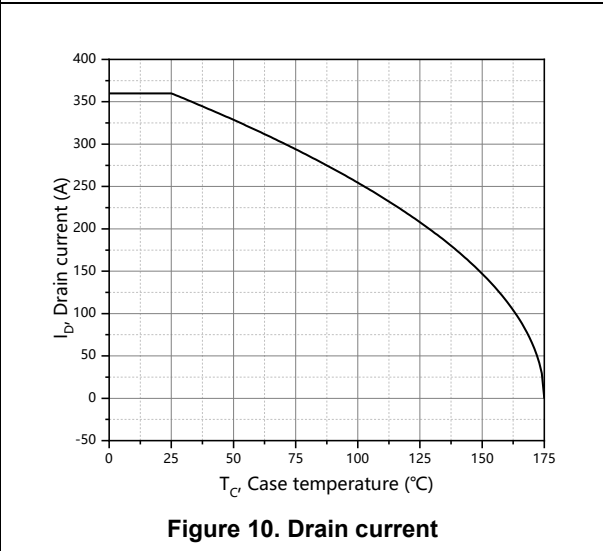
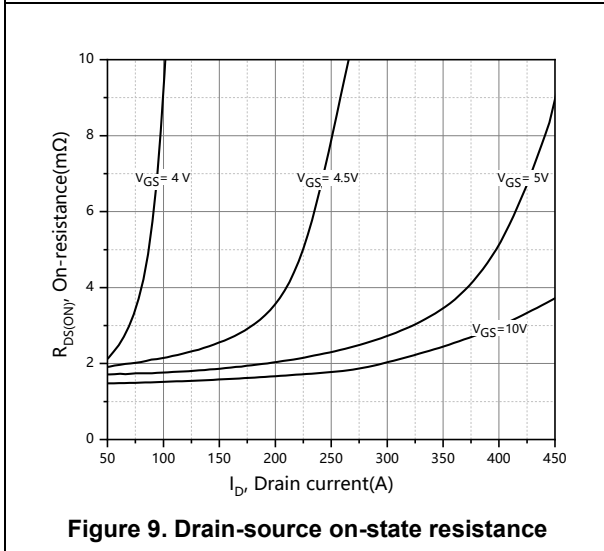
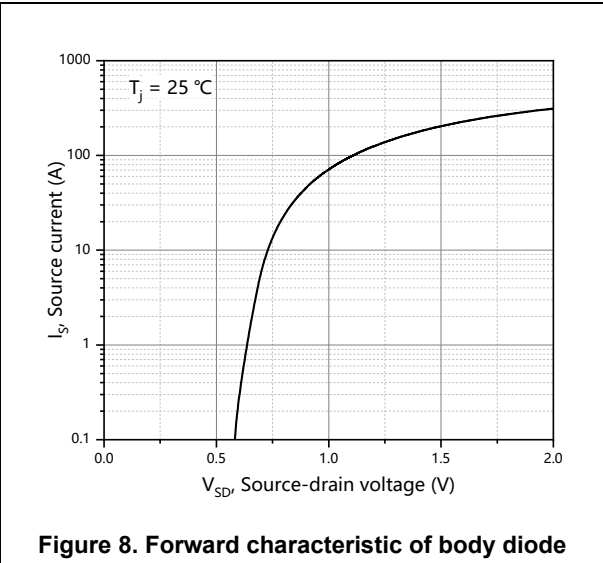
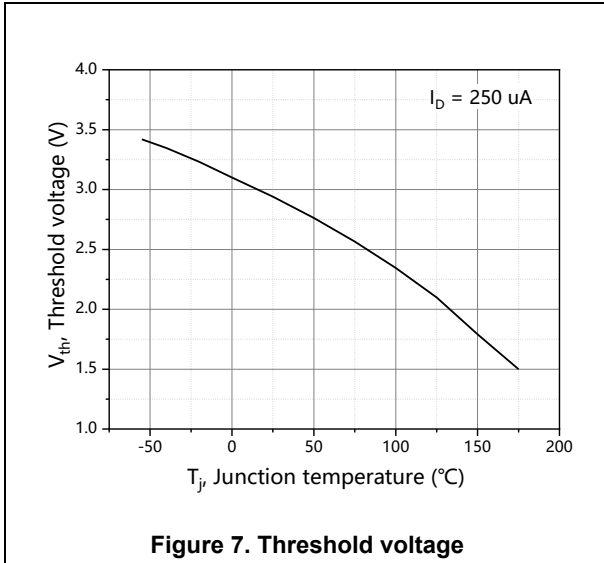


Figure 6. Drain-source on-state resistance



Test circuits and waveforms

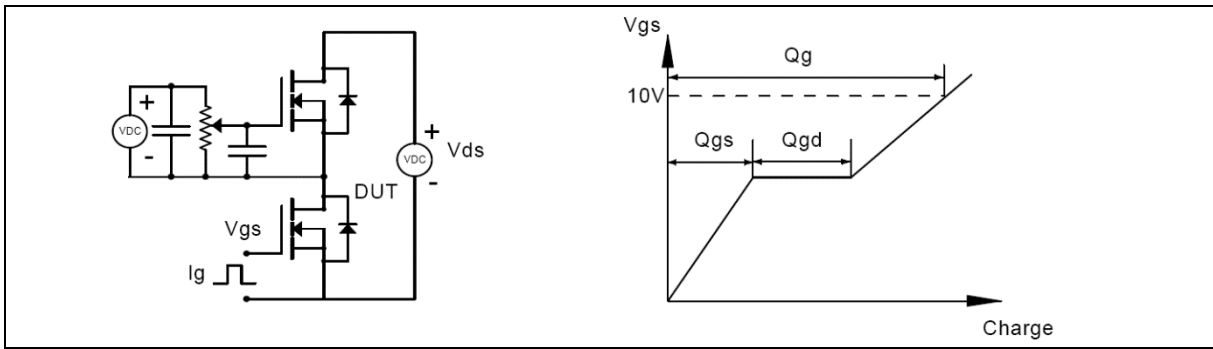


Figure 1. Gate charge test circuit & waveform



Figure 2. Switching time test circuit & waveforms

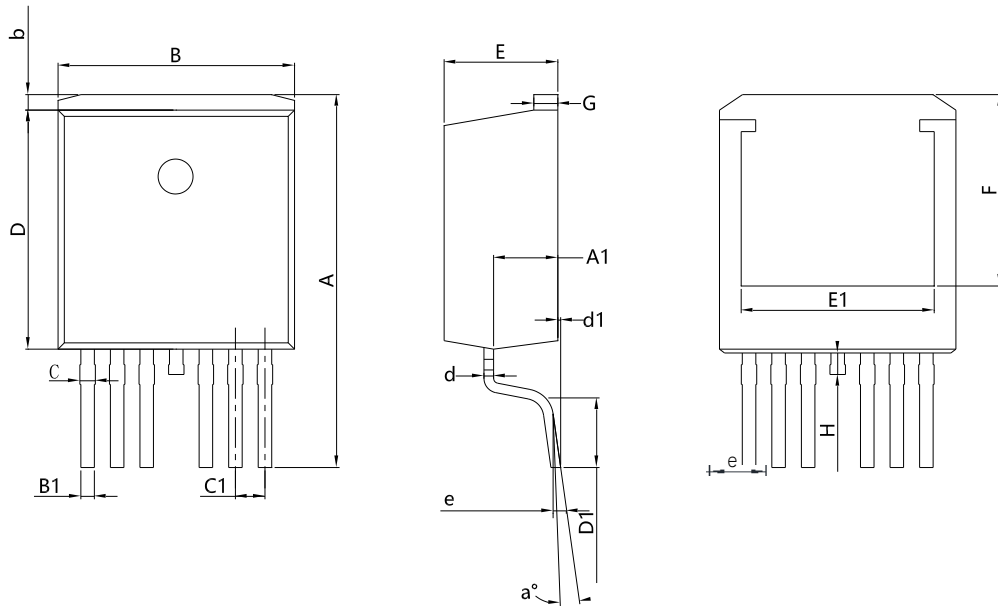


Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms



Figure 4. Diode reverse recovery test circuit & waveforms

Package Information



Symbol	mm		
	Min	Nom	Max
A	14.65	15.00	15.35
A1	2.25	2.40	2.55
B	9.80	10.00	10.20
B1	0.50	0.60	0.70
b	0.80	1.00	1.20
C	0.58	0.68	0.84
C1	1.27 BSC		
D	9.05	9.25	9.45
D1	2.40	2.70	3.00
d	0.40	0.50	0.60
d1	0.01	0.13	0.25
E	4.25	4.40	4.55
E1	7.25	-	-
F	6.90	-	-
e	0.25 BSC		
G	1.20	1.30	1.40
a	2°	5°	8°
H	0.85	1.00	1.15

Version 1: TO263 -6L-P package outline dimension

Ordering Information

Package Type	Units/ Reel	Reels / Inner Box	Units/ Inner Box	Inner Boxes/ Carton Box	Units/ Carton Box
TO263 -6L-P	800	1	800	5	4000

Product Information

Product	Package	Pb Free	RoHS	Halogen Free
SFS10R02K7NF	TO263	yes	yes	yes

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Revision History

Version	Revision History	Date
V1.0	Initial release	2022-11-18
V1.1	Update packaging information	2025-08-01